

Surface Mount Attenuator/Switch

50Ω Bi-Phase 600 to 1000 MHz

SYAS-860+



Generic photo used for illustration purposes only

CASE STYLE: TTT166

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Reel Size	Devices/Reel
7"	10, 20, 50, 100, 200
13"	500

Maximum Ratings

Operating Temperature -40°C to 85°C

Storage Temperature -55°C to 100°C

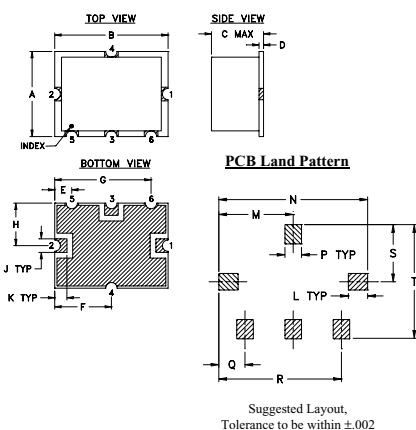
Control Current 30mA

Permanent damage may occur if any of these limits are exceeded.

Pin Connections

INPUT	1
OUTPUT	2
CONTROL	3
GROUND	4,5,6

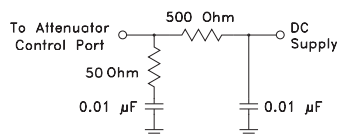
Outline Drawing



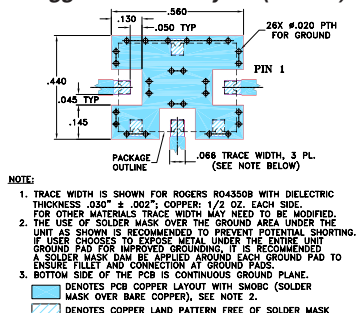
Outline Dimensions (inch/mm)

A	B	C	D	E	F	G	H	J
.38	.50	.15	.020	.075	.250	.425	.187	.050
9.65	12.70	3.81	0.51	1.91	6.35	10.80	4.75	1.27
K	L	M	N	P	Q	R	S	T
.050	.070	.270	.540	.060	.095	.445	.208	.415
1.27	1.78	6.86	13.72	1.52	2.41	11.30	5.28	10.54
								wt.
								grams
								0.8

suggested control port biasing configuration



Demo Board MCL P/N: TB-12 Suggested PCB Layout (PL-079)



Notes

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
- C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp

Features

- wideband 600 to 1000 MHz

Applications

- bi-phase modulator

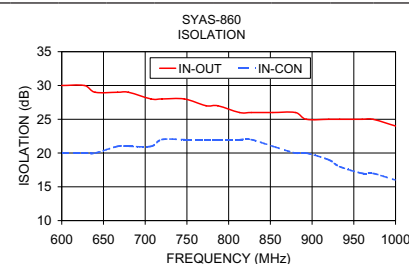
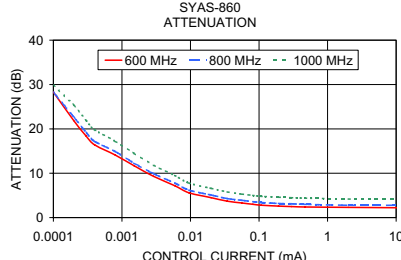
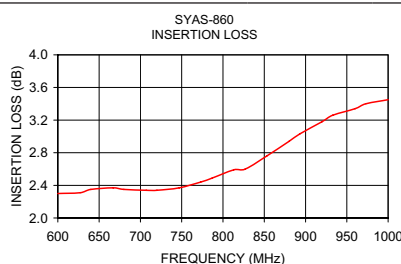
Electrical Specifications

FREQUENCY (MHz)	INSERTION LOSS (dB) ±20 mA	MAX. INPUT PWR (dBm) ±20 mA	IN-OUT ISOLATION (dB) 0 mA	BI-PHASE X (±20 mA) Typ.
IN CON	Total Range Typ. Max.	1 dB compr. no damage	Typ. Min.	Δ AMP (dB) Total Range Phase (deg.) deviation from 180°
600-1000	DC-0.05	2.7 5.7	14 25	25 18

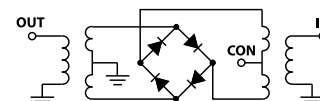
Performance specifications apply for input power up to 10 dB below stated 1 dB compression.

Typical Performance Data

Freq. (MHz)	I. Loss (dB) at 20mA		±Control ΔAMP (dB)	20mA ΔPhase (deg.)	Isolation (dB) (in-out) (in-con)		Input R. Loss (dB)	Control Current (mA)	Attenuation (dB)			Phase Δ ref at 15mA Ctrl			Input VSWR		
									600 MHz	800 MHz	1000 MHz	600 MHz	800 MHz	1000 MHz	600 MHz	800 MHz	1000 MHz
	$\bar{X}$	σ	$\bar{X}$	$\bar{X}$	$\bar{X}$	$\bar{X}$	$\bar{X}$					deg.	deg.	deg.			
600	2.30	0.015	0.07	182.1	30	20	10.8	0.0000	35.3	29.9	28.6	-60.9	-101.2	-133.3	2.9	2.3	3.1
627	2.31	0.013	0.06	182.4	30	20	11.2	0.0001	28.3	28.3	29.9	11.7	-34.3	-80.9	2.9	2.3	3.0
640	2.35	0.011	0.06	182.4	29	20	11.3	0.0002	21.8	22.6	25.3	14.5	-18.8	-51.0	2.7	2.2	2.9
667	2.37	0.007	0.06	182.6	29	21	11.4	0.0003	18.4	19.2	21.9	11.1	-16.0	-41.8	2.5	2.1	2.7
680	2.35	0.005	0.07	182.8	29	21	11.4	0.0004	16.4	17.2	19.8	9.9	-13.7	-36.0	2.4	2.0	2.6
707	2.34	0.005	0.08	182.7	28	21	11.2	0.0008	14.1	14.9	17.2	9.4	-10.4	-28.8	2.2	1.8	2.4
720	2.34	0.007	0.10	182.9	28	22	11.1	0.0015	11.7	12.3	14.5	8.8	-7.2	-21.8	1.9	1.7	2.3
747	2.37	0.008	0.13	183.0	28	22	10.7	0.0029	9.3	9.9	11.8	7.8	-4.8	-15.9	1.7	1.5	2.2
773	2.44	0.009	0.16	183.2	27	22	10.2	0.0059	7.2	7.8	9.5	6.1	-3.3	-11.3	1.4	1.4	2.2
787	2.49	0.011	0.19	183.2	27	22	10.0	0.0095	5.6	6.2	7.8	4.4	-2.3	-7.9	1.2	1.4	2.3
813	2.59	0.014	0.20	183.3	26	22	9.5	0.0200	4.5	5.1	6.6	3.1	-1.7	-5.1	1.2	1.5	2.6
827	2.60	0.018	0.24	183.6	26	22	9.2	0.0344	3.7	4.3	5.8	2.0	-1.2	-3.8	1.3	1.7	2.9
853	2.76	0.021	0.26	183.7	26	21	8.6	0.0559	3.3	3.9	5.3	1.3	-1.0	-2.7	1.4	1.8	3.2
880	2.94	0.032	0.33	183.8	26	20	8.1	0.0814	3.0	3.6	5.0	0.8	-0.9	-2.0	1.5	1.9	3.4
893	3.03	0.037	0.35	183.8	25	20	7.9	0.1072	2.8	3.4	4.8	0.7	-0.9	-1.7	1.5	1.9	3.6
920	3.18	0.040	0.40	183.9	25	19	7.4	0.1926	2.6	3.2	4.6	0.3	-0.7	-1.1	1.6	2.0	3.8
933	3.26	0.047	0.43	183.9	25	18	7.2	0.2959	2.5	3.1	4.5	0.1	-0.6	-0.8	1.6	2.1	3.9
960	3.34	0.049	0.48	183.8	25	17	6.7	0.4662	2.4	3.0	4.4	0.0	-0.5	-0.5	1.7	2.1	4.0
973	3.40	0.051	0.49	183.8	25	17	6.6	2.0106	2.3	2.8	4.2	0.0	-0.3	-0.2	1.7	2.2	4.2
1000	3.45	0.050	0.49	183.9	24	16	6.2	15.0980	2.2	2.8	4.1	0.0	-0.1	0.1	1.7	2.2	4.3



electrical schematic



REV. D
M160892
SYAS-860+
WP/TD/AM
200924

Typical Performance Data

FREQ. (MHz)	INSERTION LOSS (dB) at 20mA Control Current	AMP. UNBAL. (dB) at ± 20 mA Control Current	PHASE UNBAL. (deg.) at ± 20 mA Control Current	ISOLATION at 0 mA Control Current (dB)		RETURN LOSS (dB) Input
				In-Out	In-Con	
600.0	2.30	0.07	182.1	30	20	10.8
627.0	2.31	0.06	182.4	30	20	11.2
640.0	2.35	0.06	182.4	29	20	11.3
667.0	2.37	0.06	182.6	29	21	11.4
680.0	2.35	0.07	182.8	29	21	11.4
707.0	2.34	0.08	182.7	28	21	11.2
720.0	2.34	0.10	182.9	28	22	11.1
747.0	2.37	0.13	183.0	28	22	10.7
773.0	2.44	0.16	183.2	27	22	10.2
787.0	2.49	0.19	183.2	27	22	10.0
813.0	2.59	0.20	183.3	26	22	9.5
827.0	2.60	0.24	183.6	26	22	9.2
853.0	2.76	0.26	183.7	26	21	8.6
880.0	2.94	0.33	183.8	26	20	8.1
893.0	3.03	0.35	183.8	25	20	7.9
920.0	3.18	0.40	183.9	25	19	7.4
933.0	3.26	0.43	183.9	25	18	7.2
960.0	3.34	0.48	183.8	25	17	6.7
973.0	3.40	0.49	183.8	25	17	6.6
1000.0	3.45	0.49	183.9	24	16	6.2

CONTROL CURRENT (mA)	ATTENUATION (dB)			PHASE UNBALANCE REF AT 15 mA CONTROL (deg.)			INPUT VSWR (:1)		
	600 MHz	800 MHz	1000 MHz	600 MHz	800 MHz	1000 MHz	600 MHz	800 MHz	1000 MHz
0.0000	35.3	29.9	28.6	-60.9	-101.2	-133.3	2.9	2.3	3.1
0.0001	28.3	28.3	29.9	11.7	-34.3	-80.9	2.9	2.3	3.0
0.0002	21.8	22.6	25.3	14.5	-18.8	-51.0	2.7	2.2	2.9
0.0003	18.4	19.2	21.9	11.1	-16.0	-41.8	2.5	2.1	2.7
0.0004	16.4	17.2	19.8	9.9	-13.7	-36.0	2.4	2.0	2.6
0.0008	14.1	14.9	17.2	9.4	-10.4	-28.8	2.2	1.8	2.4
0.0015	11.7	12.3	14.5	8.8	-7.2	-21.8	1.9	1.7	2.3
0.0029	9.3	9.9	11.8	7.8	-4.8	-15.9	1.7	1.5	2.2
0.0059	7.2	7.8	9.5	6.1	-3.3	-11.3	1.4	1.4	2.2
0.0095	5.6	6.2	7.8	4.4	-2.3	-7.9	1.2	1.4	2.3
0.0200	4.5	5.1	6.6	3.1	-1.7	-5.1	1.2	1.5	2.6
0.0344	3.7	4.3	5.8	2.0	-1.2	-3.8	1.3	1.7	2.9
0.0559	3.3	3.9	5.3	1.3	-1.0	-2.7	1.4	1.8	3.2
0.0814	3.0	3.6	5.0	0.8	-0.9	-2.0	1.5	1.9	3.4
0.1072	2.8	3.4	4.8	0.7	-0.9	-1.7	1.5	1.9	3.6
0.1926	2.6	3.2	4.6	0.3	-0.7	-1.1	1.6	2.0	3.8
0.2959	2.5	3.1	4.5	0.1	-0.6	-0.8	1.6	2.1	3.9
0.4662	2.4	3.0	4.4	0.0	-0.5	-0.5	1.7	2.1	4.0
2.0106	2.3	2.8	4.2	0.0	-0.3	-0.2	1.7	2.2	4.2
15.0980	2.2	2.8	4.1	0.0	-0.1	0.1	1.7	2.2	4.3

REV. X1
SYAS-860+
061204
Page 1 of 1



IF/RF MICROWAVE COMPONENTS • ISO 9001 ISO 14001 AS9100 CERTIFIED • RoHS compliant
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661

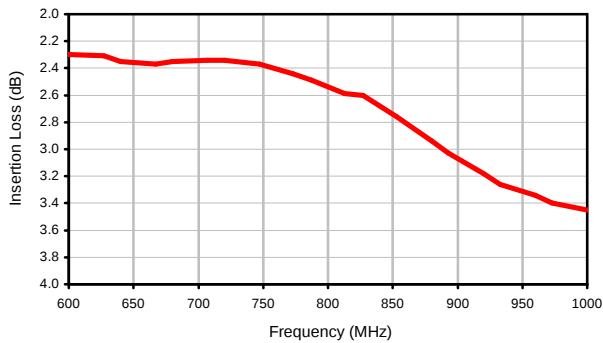


The Design Engineers Search Engine finds the model you need, Instantly • For detailed performance specs & shopping online see

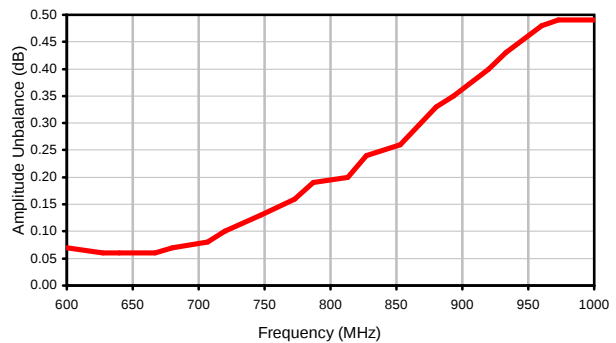


Typical Performance Curves

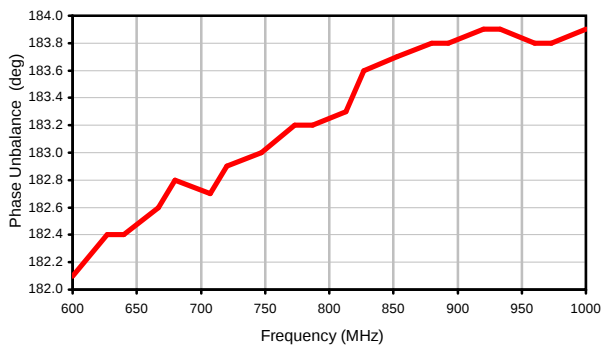
Insertion Loss @ 20 mA



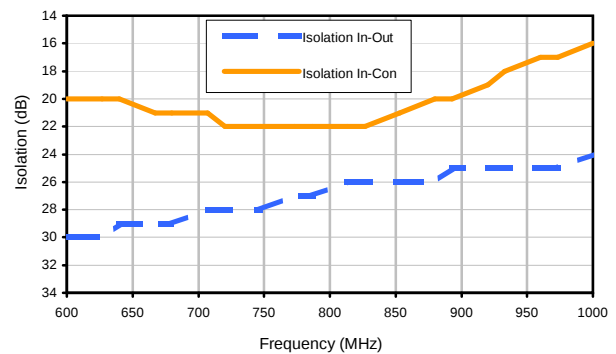
Amplitude Unbalance @ ± 20 mA



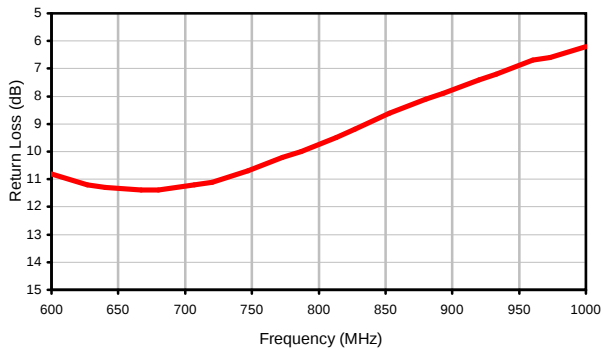
Phase Unbalance @ ± 20 mA



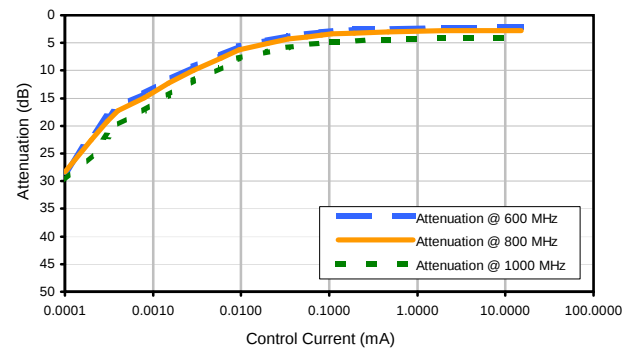
Isolation @ 0 mA



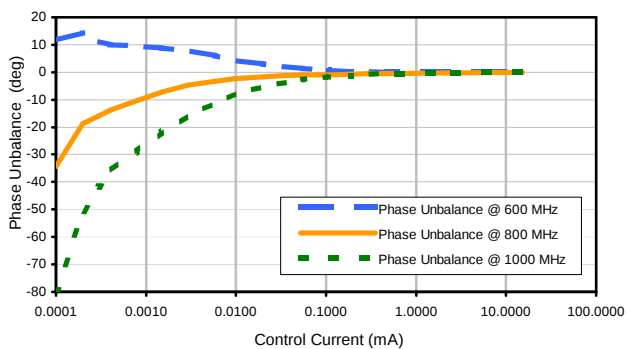
Return Loss Input



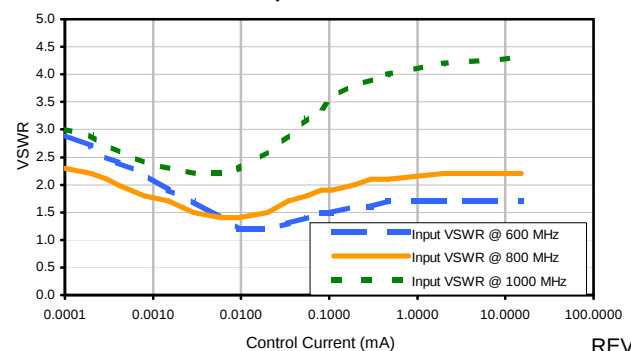
Attenuation



Phase Unbalance ref @ 15 mA



Input VSWR



REV. X1
SYAS-860+
061204
Page 1 of 1



IF/RF MICROWAVE COMPONENTS • ISO 9001 ISO 14001 AS9100 CERTIFIED RoHS compliant
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661

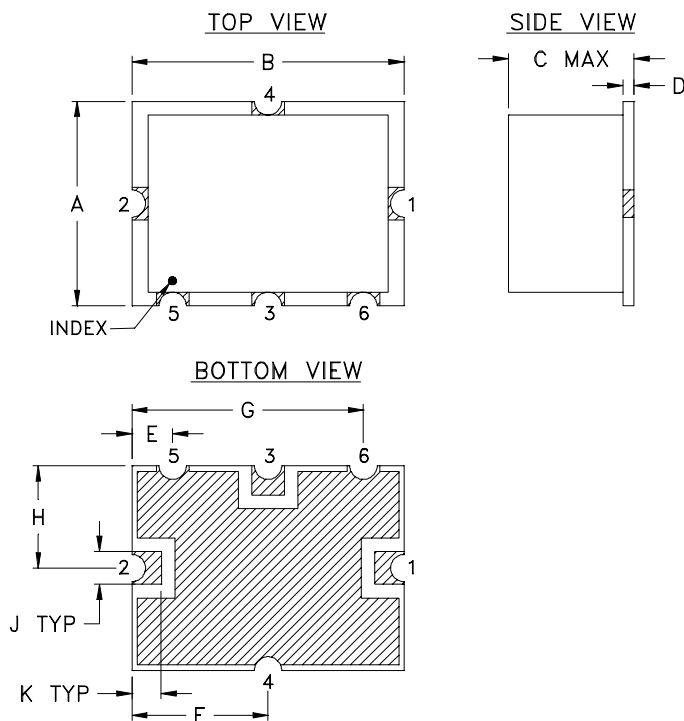


The Design Engineers Search Engine finds the model you need, Instantly • For detailed performance specs & shopping online see

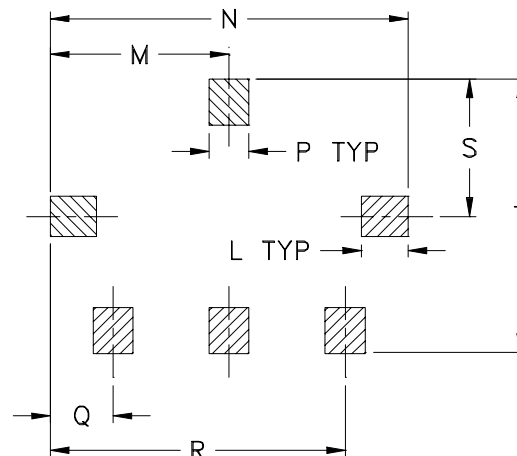


Outline Dimensions

TTT166
TTT167



PCB Land Pattern



Suggested Layout,
Tolerance to be within $\pm .002$

CASE #	A	B	C	D	E	F	G	H	J	K	L	M	N
TTT166	.38 (9.65)	.50 (12.70)	.15 (3.81)	.020 (0.51)	.075 (1.91)	.250 (6.35)	.425 (10.80)	.187 (4.75)	.050 (1.27)	.050 (1.27)	.070 (1.78)	.270 (6.86)	.540 (13.72)
TTT167			.23 (5.84)										

CASE #	P	Q	R	S	T	WT. GRAM
TTT166	.060 (1.52)	.095 (2.41)	.445 (11.30)	.208 (5.28)	.415 (10.54)	.8
TTT167						.8

Dimensions are in inches (mm). Tolerances: 2 Pl. $\pm .01$; 3 Pl. $\pm .005$

Note:

- Case material: Plastic.
- Base material: Printed wiring laminate.
- Termination finish:
 - For RoHS Case Styles: 3-5 μ inch (.08-.13 microns) Gold over 120-240 μ inch (3.05-6.10 microns) Nickel plate. All models, (+) suffix.
 - For RoHS-5 Case Styles: Tin-Lead plate. All models, no (+) suffix.

Tape & Reel Packaging TR-F12



Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel	
24	12	7	Small quantity standards (see note)	10
				20
				50
				100
				200
		13	Standard	500

Note: Please Consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf



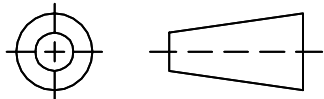
INTERNET <http://www.minicircuits.com>

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661

Distribution Centers NORTH AMERICA 800-654-7949 • 417-335-5935 • Fax 417-335-5945 • EUROPE 44-1252-832600 • Fax 44-1252-837010

Mini-Circuits ISO 9001 & ISO 14001 Certified

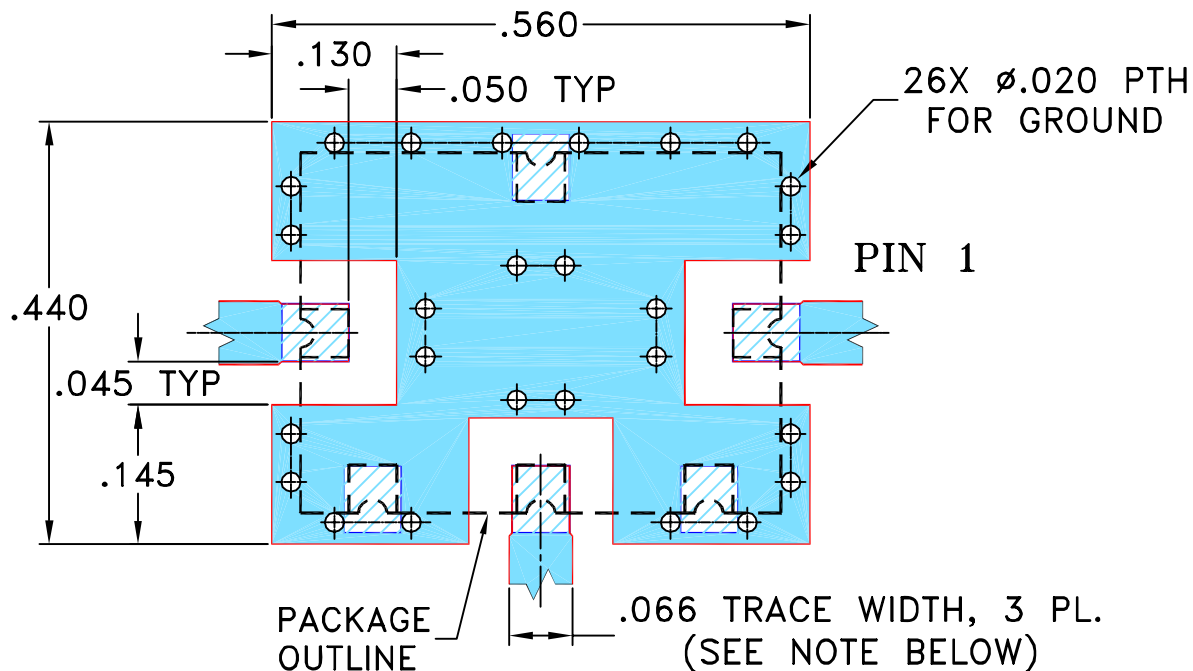
THIRD ANGLE PROJECTION



REVISIONS

REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
A	M86762	ADDED CONNECTIONS "lp & lq"	05/23/03	MMG	WL
B	M94598	ADDED CONNECTION "hk"	10/08/04	MMG	HY
C	M102713	UPDATED NOTES & DESCRIPTION	01/14/06	GF	IL
D	M132989	UPDATED NOTE 2	08/24/11	GF	DJ

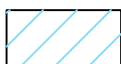
**SUGGESTED MOUNTING CONFIGURATION FOR
TTT166/167 CASE STYLE, "hk"/"lp"/"lq"
"x"/"ck"/"ec" PIN CONNECTIONS**

**NOTE:**

1. TRACE WIDTH IS SHOWN FOR ROGERS R04350B WITH DIELECTRIC THICKNESS .030" $\pm$.002"; COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. THE USE OF SOLDER MASK OVER THE GROUND AREA UNDER THE UNIT AS SHOWN IS RECOMMENDED TO PREVENT POTENTIAL SHORTING. IF USER CHOOSES TO EXPOSE METAL UNDER THE ENTIRE UNIT GROUND PAD FOR IMPROVED GROUNDING, IT IS RECOMMENDED A SOLDER MASK DAM BE APPLIED AROUND EACH GROUND PAD TO ENSURE FILLET AND CONNECTION AT GROUND PADS.
3. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.



DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER), SEE NOTE 2.



DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

UNLESS OTHERWISE SPECIFIED

INITIALS

DATE

DIMENSIONS ARE IN INCHES

TOLERANCES ON:

2 PL DECIMALS $\pm$ 3 PL DECIMALS $\pm$.005ANGLES $\pm$ FRACTIONS $\pm$

DRAWN

GF

03/18/03

CHECKED

IL

04/15/03

APPROVED

DJ

04/15/03

**Mini-Circuits®**13 Neptune Avenue
Brooklyn NY 11235

PL, hk/lp/lq/x/ck/ec, TTT166/167,
SYM/HJK/SYAS/SYPD, TB-12

SIZE
ACODE IDENT
15542DRAWING NO:
98-PL-079REV:
D

FILE: 98PL079

SCALE: 5:1

SHEET: 1 OF 1

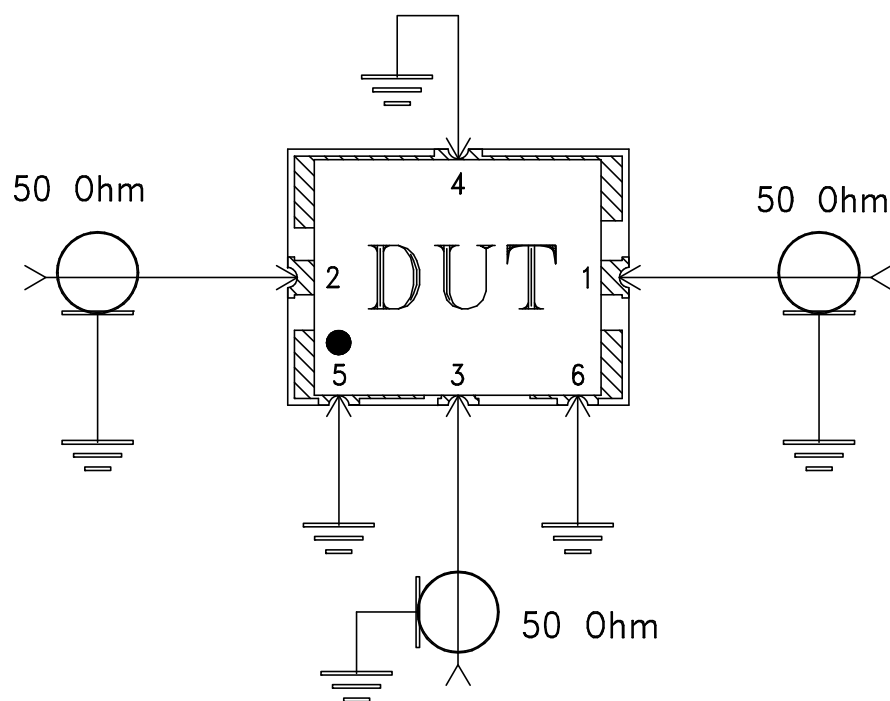
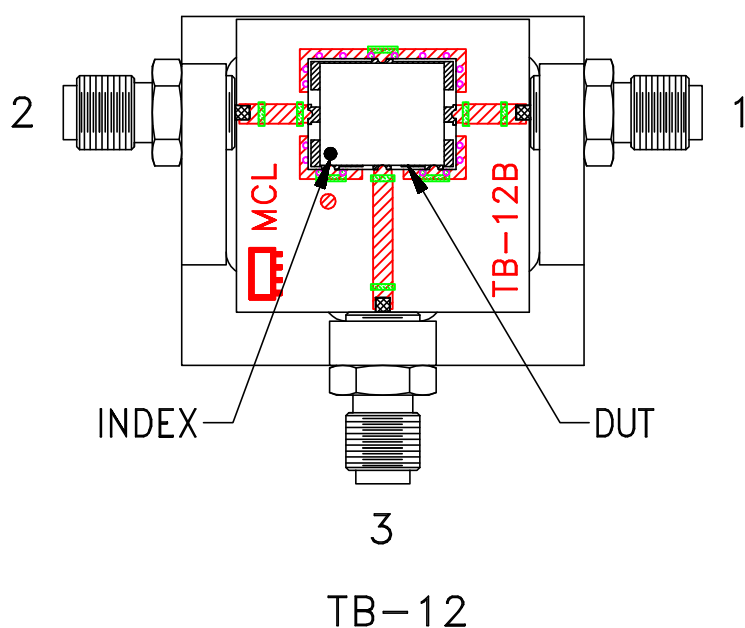
Mini-Circuits®

THIS DOCUMENT AND ITS CONTENTS ARE THE PROPERTY OF MINI-CIRCUITS. EXCEPT FOR USE EXPRESSLY GRANTED, IN WRITING, TO ITS VENDORS, VENDEE AND THE UNITED STATES GOVERNMENT, MINI-CIRCUITS RESERVES ALL PROPRIETARY DESIGN, USE, MANUFACTURING AND REPRODUCTION RIGHTS THERETO. THESE CONTENTS SHALL NOT BE USED, DUPLICATED OR DISCLOSED TO ANY OUTSIDE PARTY, IN WHOLE OR IN PART, WITHOUT WRITTEN PERMISSION OF MINI-CIRCUITS.

ASHEETA1.DWG REV:A DATE:01/12/95

Evaluation Board and Circuit

For Pin Connections Refer to Data Sheet of the DUT



Schematic Diagram

Notes:

1. SMA Female connectors.
2. PCB Material: Rogers R04350 or equivalent,
Dielectric Constant=3.5, Thickness=.030 inch.

 **Mini-Circuits®**



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215